

WHAT IS CLAIMED IS:

1. An organic film vapor deposition method comprising:

5 a first step of supporting a substrate formed with a scintillator on at least three protrusions of a target-support element disposed on a vapor deposition table so as to keep a distance from said vapor deposition table;

10 a second step of introducing said vapor deposition table having said substrate supported by said target-support element into a vapor deposition chamber of a CVD apparatus; and

15 a third step of depositing an organic film by CVD method onto all surfaces of said substrate, provided with said scintillator, introduced into said vapor deposition chamber in a state that said substrate is supported so as to keep a distance from said vapor deposition table.

2. An organic film vapor deposition method according to claim 1, wherein said target-support element is constituted by at least three target-support needles.

20 3. An organic film vapor deposition method according to claim 1, wherein said target-support element is constituted by a strand member.

25 4. An organic film vapor deposition method according to claim 1, wherein said organic film is a polyparaxylylene film.

5. A scintillator panel with organic film

deposited by the method according to claim 1.

6. A scintillator panel comprising:

a substrate;

a scintillator formed on said substrate; and

5 an organic film covered substantial all surfaces of
said substrate not only over the scintillator side but also
over the opposite side.

7. A scintillator panel according to claim 6,
wherein said organic film is a polyparaxylylene film.

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